2017 Technology Seminar

TRI innovation

Inspection and Testing for the Smart Factory

date. . . . .
18 MAY 2017

time. . .
9:00 16:00

venue. . . . .
Eastin Hotel Penang, Malaysia

Agenda

Time	Session	
9:20~9:40	**Registration**	Registration and Morning snack
10:00~10:20	**Welcome Note**	Seminar opening
10:20~10:50	**3D SPI**	Speed and Automation in 3D SPI
10:50~11:40	**3D and CI AOI**	Flexible 3D and UV AOI Systems
11:40~12:00	**Product Demo**	Live on-site hands-on demo
12:00~13:30	**Lunch**	Networking and refreshments
13:30~14:20	**AXI, CT Inspection**	New CT Applications and NPI Solutions
14:20~15:00	**Multi-core ICT Testing**	Introducing new Award-winning TR5001 SII Series ICT
15:00~15:30	**YMS 4.0 for Industry 4.0**	
15:30~16:00	**Q&A & Pop Quiz**	
16:00	**Tea Break & Demo**	

New Products

TR7007QI 3D SPI
High Performance Stop-and-go 3D SPI with 4-way digital fringe pattern projection and rapid CoaXPress imaging.

TR7700QE 3D AOI
High Performance Stop-and-go 3D AOI with 4-way digital fringe pattern projection, 3D solder inspection and 3D laser option.

TR7600XLL SII CT 3D AXI
New 3D X-ray Inspection System with high-speed inspection and built-in CT function for detailed 3D solder joint review.

TR5001Q SII INLINE ICT
New multi-core ICT offers improved accuracy, parallel testing and high throughput while reducing operator workload.

To register, please contact:
Ms. Tzeting Ng Tel: **+60-4-646-1171** or Email: **Tzeting_Ng@tri.com.tw**

REGISTER ONLINE!

Company:		Your TRI Sales:		
	Name	**Phone**	**E-Mail**	**Vegetarian?**
1				☐ Yes ／ ☐ No
2				☐ Yes ／ ☐ No
3				☐ Yes ／ ☐ No

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